

9531/9131

SMT Stiftheisen - RM 2,54 mm - liegend - geprägte Kontakte

SMT Header - Pitch 2,54 mm - Horizontal Type - Stamped Contacts

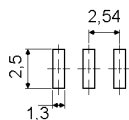
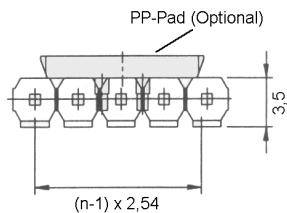
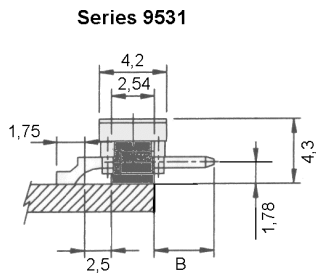
Technische Daten / Technical Data:

| | |
|--|---|
| Isolierkörper <i>Insulator</i> | Thermoplastischer Kunststoff, nach UL94V0 <i>Thermoplastic, rated UL94V0</i> |
| Kontaktmaterial <i>Contact Material</i> | Vierkantstift □ 0,635 mm, CuZn 30 <i>Square Pin □ 0,635 mm, CuZn 30</i> |
| Kontaktfläche <i>Contact Surface</i> | lt. Oberflächenoptionen, über Ni (1,3-2,5 µm) <i>acc. to options (see below), over Ni (1,3-2,5 µm)</i> |
| Lötbarkeit <i>Solderability</i> | IEC512-12A <i>IEC512-12A</i> |
| Durchgangswiderstand <i>Contact Resistance</i> | ≤ 20 mOhm <i>≤ 20 mOhm</i> |
| Isolationswiderstand <i>Insulation Resistance</i> | > 10 ⁹ Ohm <i>> 10⁹ Ohm</i> |
| Spannungsfestigkeit <i>Test Voltage</i> | 1000 V _{DC} <i>1000 V_{DC}</i> |
| Nennspannung <i>Current Voltage</i> | 250 V _{AC} <i>250 V_{AC}</i> |
| Nennstrom <i>Current Rating</i> | 3 A <i>3 A</i> |
| Temperaturbereich <i>Temperature Range</i> | -55°C...+125°C <i>-55°C...+125°C</i> |
| Verarbeitung <i>Processing</i> | Reflow-Lötverfahren; weitere Informationen in Kapitel T <i>Reflow-Soldering, further informations in chapter T</i> |

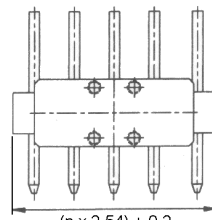


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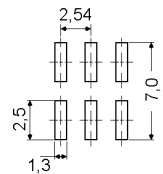
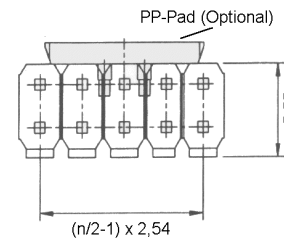
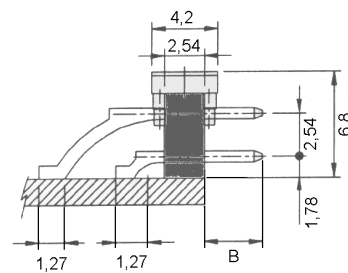
Passende Buchsenleisten Serie:
Mates with Female Headers Series:
3490 / 3491 / 1531 / 1532 / 3882



PCB-Layout



Series 9131



PCB-Layout

n = Anzahl der Kontakte
n = No. of Contacts

| Series | Dimensions* | Contacts* | Plating* | Packing* |
|---|---|---|--|--------------------|
| 9531 | 14 | 012 | 50 | PPTR |
| 9531 einreihig <i>single row</i> 9131 zweireihig <i>double row</i> | 13 = B : 3,05 14 = B : 5,84 15 = B : 8,13 | 002-040 pol. einreihig <i>single row</i> 004-080 pol. zweireihig <i>double row</i> | 00 = vergoldet <i>gold plated</i> 50 = verzinnt <i>tin plated</i> 60 = sel. Au/Sn <i>duplex plating Au/Sn</i> | 00 PPST PPTR |

Weitere Stiftlängen und Oberflächenveredelungen auf Anfrage.
Other contact lengths and plating options upon request.

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.
** Order example - To be replaced by your specifications.*)

Lieferformen / Packing Options:

00 = Schüttgut ohne PP-Pad / *bulk goods w/o PP-Pad*

PPST = in Stangen mit PP-Pad / *in tubes w/ PP-Pad*

PPTR = mit PP-Pad, Tape & Reel Verpackung / *Tape & Reel Packing w/ PP-Pad*

Informationen zum Reflow-Lötverfahren

Reflow-Soldering Informations

Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflowverfahren verarbeitet werden (Maximalwerte):

| Profil Eigenschaft | Bleifreies Lötten |
|---|-----------------------------------|
| Durchschnitts-Ramp-Up Rate ($T_{s_{max}}$ to T_p) | 3 °C / Sek. Max. |
| Vorheizen - Temperatur Min ($T_{s_{min}}$) - Temperatur Max ($T_{s_{max}}$) - Zeit ($t_{s_{min}}$ auf $t_{s_{max}}$) | 150°C 200°C 60-180 Sekunden |
| Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L) | 217°C 60-150 Sekunden |
| Peak/Klassifizierung Temperatur (T_p) | 260°C +/- 5°C |
| Zeit innerhalb von 5°C um die Peak-Temperatur (t_p) | 20-40 Sekunden |
| Ramp-Down Rate | 6°C / Sekunde max. |
| Zeit von 25°C bis zur Peak-Temperatur | 8 Minuten max. |

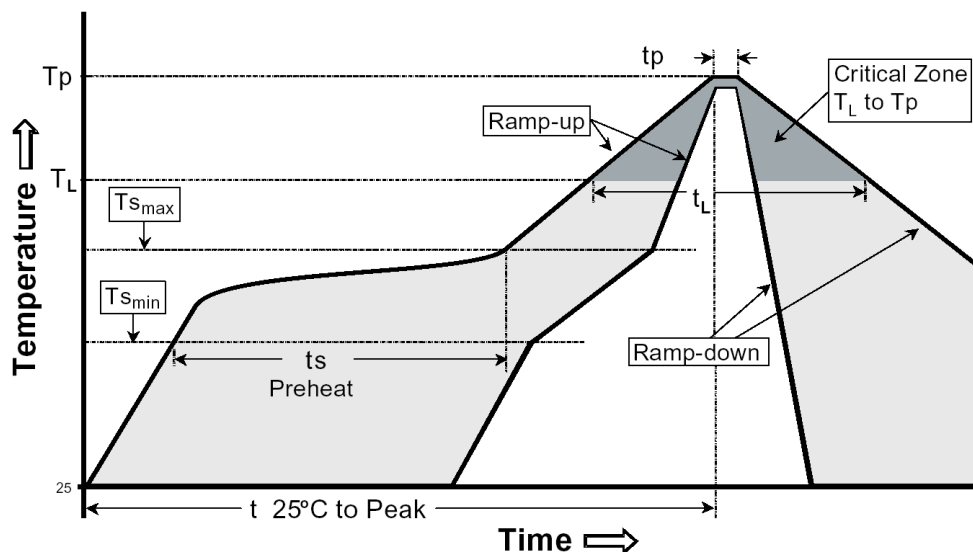
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Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

| Profile Feature | PB-Free assembly |
|--|----------------------------------|
| Average Ramp-Up Rate ($T_{s_{max}}$ to T_p) | 3 °C / second max. |
| Preheat - Temperature Min ($T_{s_{min}}$) - Temperature Max ($T_{s_{max}}$) - Time ($t_{s_{min}}$ to $t_{s_{max}}$) | 150°C 200°C 60-180 seconds |
| Time maintained above: - Temperature (T_L) - Time (t_L) | 217°C 60-150 seconds |
| Peak/Classification Temperature (T_p) | 260°C +/- 5°C |
| Time within 5°C of actual Peak Temperature (t_p) | 20-40 seconds |
| Ramp-Down Rate | 6°C / second max. |
| Time 25°C to Peak Temperature | 8 minutes max. |

Empfohlenes Reflow-Lötprofil:

Recommended Reflow-Soldering profile:



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